



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	14-10-2022
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G031G6U7 STM32G031G6U7TR	78MB*466XXXY	A	998Z	14-10-2022
Amount	UoM	Unit type	ST ECOPACK Grade	
23.64	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au), ENI	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	4x4x0.55	28	flat	
Comment	Package : A0B0 UFQFPN 4X4X0.55 28L PITCH0.5 COL 8202209			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	78M8*466XXX				5000000.0	999966.4				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	1.430	mg	supplier	die	Silicon (Si)	7440-21-3		1.290	mg	902098	54566				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	4895	296				
				supplier	metallization	Copper (Cu)	7440-50-8		0.059	mg	41259	2496				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.019	mg	13287	804				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	699	42				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	699	42				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.015	mg	10490	634				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.038	mg	26573	1607				
				DA_EPOXY FILM HR-5104T-25_SD	M-011 Other inorganic materials	0.487	mg	Supplier	Organic Compounds	Epoxy Resin A	Trade Secret		0.046	mg	95238	1960
								Supplier	Organic Compounds	Epoxy Resin B	Trade Secret		0.070	mg	142857	2941
Supplier	Organic Compounds	Phenol Resin	Trade Secret						0.070	mg	142857	2941				
Supplier	Organic Compounds	SiO2 Filler	Trade Secret						0.232	mg	476190	9802				
Supplier	Metals	(Meta)Acrylic Copolymer	Trade Secret						0.070	mg	142857	2941				
Mold Compound_EME-G770HCD_Sum	M-011 Other inorganic materials	9.614	mg	Supplier	Organic Compounds	Epoxy Resin	Trade Secret		0.202	mg	21000	8540				
				Supplier	Organic Compounds	Phenol Resin	Trade Secret		0.202	mg	21000	8540				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		8.041	mg	836450	340147				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		1.109	mg	115320	46895				
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.060	mg	6230	2533				
GOLD WIRE AU HA3 TYPE_HERAEUS	Bonding Wire	0.230	mg	Supplier	Metals	Gold	7440-57-5		0.230	mg	1000000	9721				
Leadframe_C7025+Ni/Pd/Au-Ag_HDS	Copper & its alloys	11.880	mg	Supplier	Metals	Copper	7440-50-8		11.478	mg	966120	485493				
				Supplier	Metals	Nickel	7440-02-0		0.353	mg	29750	14950				
				Supplier	Metals	Silicon	7440-21-3		0.031	mg	2600	1307				
				Supplier	Metals	Magnesium	7439-95-4		0.014	mg	1150	578				
				Supplier	Metals	Silver	7440-22-4		0.001	mg	80	40				
				Supplier	Metals	Gold	7440-57-5		0.001	mg	100	50				
				Supplier	Metals	Palladium	7440-05-3		0.002	mg	200	101				